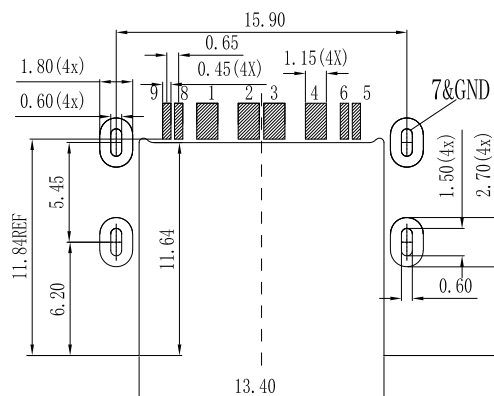
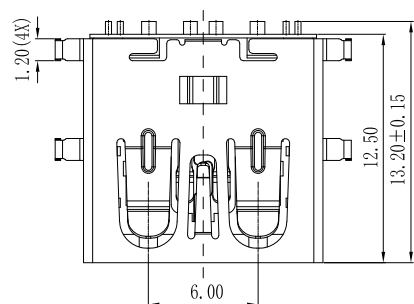
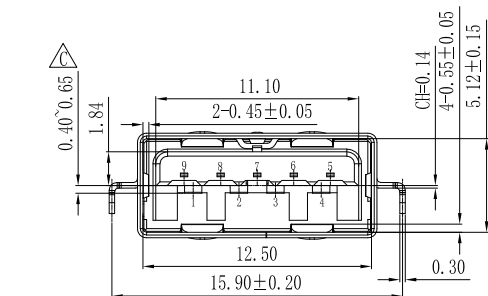
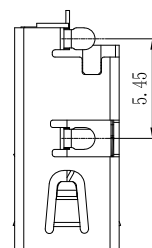
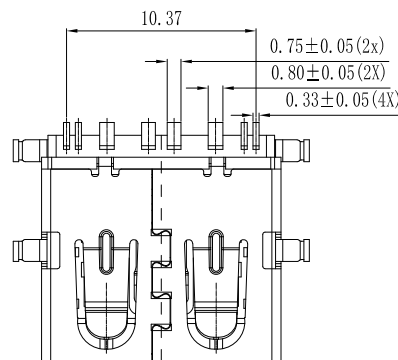
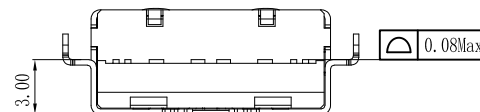
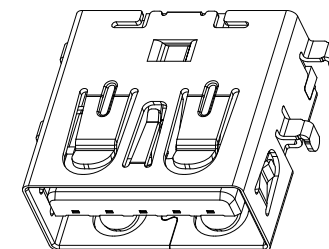




TOLERANCE: ± 0.05 , RECOMMENDED PCB LAYOUT
(TOP VIEW)

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

NOTE:

1. MATERIAL:

- 1.1 INSULATOR: LCP+30%GF, UL94 V-0.
- 1.2 CONTACT 1~4PIN: C5191-EH.
- 1.3 CONTACT 5~9PIN: C5191-EH.
- 1.4 SHELL: SUS304 3/4H

2. PLATING:

- 2.1 CONTACT:
CONTACT AREA: GOLD PLATING.
SOLDER AREA: 100u" Min MATTE TIN PLATING.
UNDER PLATE: 50u" Min NICKEL PLATING.
- 2.2 SHELL: 50u" Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:

- 3.1 ELECTRICAL CHARACTERISTICS:
CONTACT RESISTANCE: 30mΩ MAXIMUM
CONTACT CURRENT RATING: 3A
DIELECTRIC WITHSTANDING VOLTAGE: 500 V R.M.S.
INSULATION RESISTANCE: 100 MEGOHMS MIN
OPERATING TEMPERATURE: -25° C ~ +85° C

3.2 MECHANICAL:

- MATING FORCE: 8-25N .
UNMATING FORCE: 10-25N .

After lifespan testing: 6N Min.

4. PART MUST COMPLY ROHS SPECIFICATION

5. WAVE SOLDER: THE CONNECTOR SHALL BE MOUNTED ON THE PCB. THE TEMPERATURE OF THE SOLDER SHALL BE 260 ± 5 ° C AND IMMERSION DURATION 5 SECONDS.

6. ROHS, HF

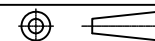


深圳市华宇创精密电子有限公司

TOLERANCE:

XX ± 0.30
XX ± 0.25
XXX ± 0.15

X° $\pm 2^\circ$ X.X° $\pm 0.5^\circ$



UNIT: mm [inch]

SCALE: 1:1

SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

USB 3.1 AF 10Gbps 沉板 H=3.0mm

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYCW185-USBA09-300B

APPROVED BY:

邱敏

DATE :

2014-02-23

DRAW NO:

HYC-2604281556

SHEET NO.

1 OF 1